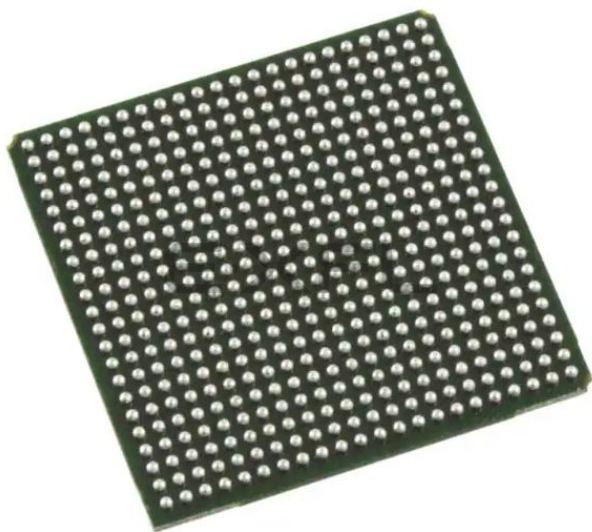




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	4000
Number of Logic Elements/Cells	32000
Total RAM Bits	339968
Number of I/O	331
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-35e-5f484c

ROM Mode

ROM mode uses the LUT logic; hence, Slices 0 through 3 can be used in ROM mode. Preloading is accomplished through the programming interface during PFU configuration.

Routing

There are many resources provided in the LatticeECP2/M devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU). The x1 and x2 connections provide fast and efficient connections in horizontal and vertical directions. The x2 and x6 resources are buffered, allowing the routing of both short and long connections between PFUs.

The LatticeECP2/M family has an enhanced routing architecture that produces a compact design. The Diamond design software takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

sysCLOCK Phase Locked Loops (GPLL/SPLL)

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. All the devices in the LatticeECP2/M family support two General Purpose PLLs (GPLLs) which are full-featured PLLs. In addition, some of the larger devices have two to six Standard PLLs (SPLLs) that have a subset of GPLL functionality.

General Purpose PLL (GPLL)

The architecture of the GPLL is shown in Figure 2-5. A description of the GPLL functionality follows.

CLKI is the reference frequency (generated either from the pin or from routing) for the PLL. CLKI feeds into the Input Clock Divider block. The CLKFB is the feedback signal (generated from CLKOP or from a user clock PIN/logic). This signal feeds into the Feedback Divider. The Feedback Divider is used to multiply the reference frequency.

The Delay Adjust Block adjusts either the delays of the reference or feedback signals. The Delay Adjust Block can either be programmed during configuration or can be adjusted dynamically. The setup, hold or clock-to-out times of the device can be improved by programming a delay in the feedback or input path of the PLL, which will advance or delay the output clock with reference to the input clock.

Following the Delay Adjust Block, both the input path and feedback signals enter the Voltage Controlled Oscillator (VCO) block. In this block the difference between the input path and feedback signals is used to control the frequency and phase of the oscillator. A LOCK signal is generated by the VCO to indicate that the VCO has locked onto the input clock signal. In dynamic mode, the PLL may lose lock after a dynamic delay adjustment and not relock until the t_{LOCK} parameter has been satisfied. LatticeECP2/M devices have two dedicated pins on the left and right edges of the device for connecting optional external capacitors to the VCO. This allows the PLLs to operate at a lower frequency. This is a shared resource that can only be used by one PLL (GPLL or SPLL) per side.

The output of the VCO then enters the post-scalar divider. The post-scalar divider allows the VCO to operate at higher frequencies than the clock output (CLKOP), thereby increasing the frequency range. A secondary divider takes the CLKOP signal and uses it to derive lower frequency outputs (CLKOK). The Phase/Duty Select block adjusts the phase and duty cycle of the CLKOP signal and generates the CLKOS signal. The phase/duty cycle setting can be pre-programmed or dynamically adjusted.

The primary output from the post scalar divider CLKOP along with the outputs from the secondary divider (CLKOK) and Phase/Duty select (CLKOS) are fed to the clock distribution network.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becomes active.

These instructions apply to all EBR RAM and ROM implementations.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled.

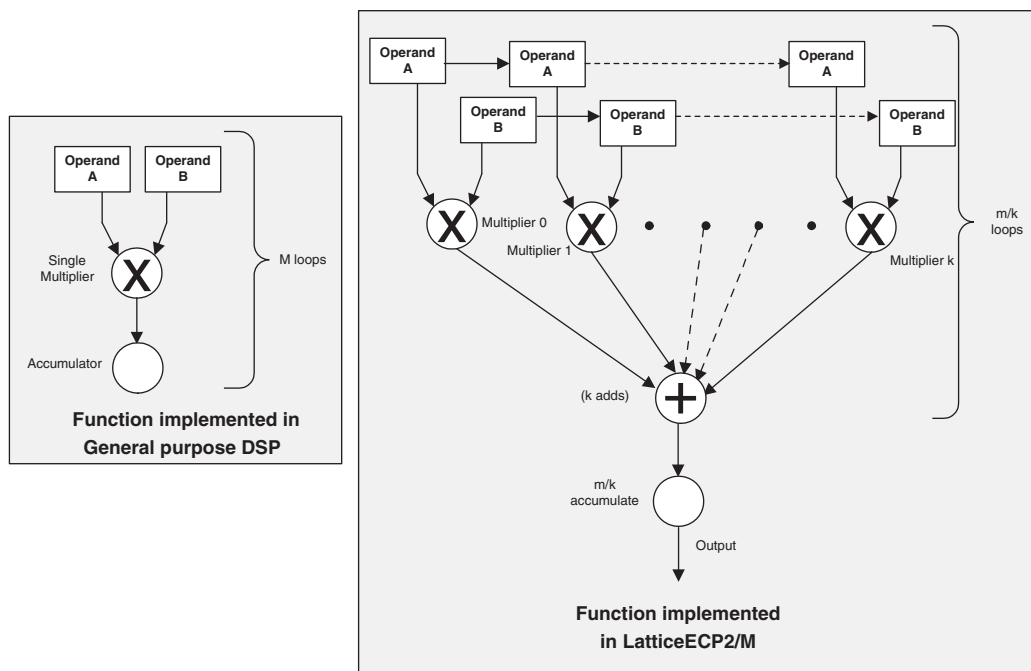
sysDSP™ Block

The LatticeECP2/M family provides a sysDSP block, making it ideally suited for low cost, high performance Digital Signal Processing (DSP) applications. Typical functions used in these applications are Finite Impulse Response (FIR) filters, Fast Fourier Transforms (FFT) functions, Correlators, Reed-Solomon/Turbo/Convolution encoders and decoders. These complex signal processing functions use similar building blocks such as multiply-adders and multiply-accumulators.

sysDSP Block Approach Compared to General DSP

Conventional general-purpose DSP chips typically contain one to four (Multiply and Accumulate) MAC units with fixed data-width multipliers; this leads to limited parallelism and limited throughput. Their throughput is increased by higher clock speeds. The LatticeECP2/M, on the other hand, has many DSP blocks that support different data-widths. This allows the designer to use highly parallel implementations of DSP functions. The designer can optimize the DSP performance vs. area by choosing an appropriate level of parallelism. Figure 2-22 compares the fully serial and the mixed parallel and serial implementations.

Figure 2-22. Comparison of General DSP and LatticeECP2/M Approaches



sysDSP Block Capabilities

The sysDSP block in the LatticeECP2/M family supports four functional elements in three 9, 18 and 36 data path widths. The user selects a function element for a DSP block and then selects the width and type (signed/unsigned) of its operands. The operands in the LatticeECP2/M family sysDSP Blocks can be either signed or unsigned but not mixed within a function element. Similarly, the operand widths cannot be mixed within a block. In the LatticeECP2/M family the DSP elements can be concatenated.

The resources in each sysDSP block can be configured to support the following elements:

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{IL}, I_{IH}^{1,2}$	Input or I/O Low Leakage	$0 \leq V_{IN} \leq (V_{CCIO} - 0.2V)$	—	—	10	μA
$I_{IH}^{1,3}$	Input or I/O High Leakage	$(V_{CCIO} - 0.2V) < V_{IN} \leq 3.6V$	—	—	150	μA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7 V_{CCIO}$	-30	—	-210	μA
I_{PD}	I/O Active Pull-down Current	$V_{IL} (MAX) \leq V_{IN} \leq V_{IH} (MAX)$	30	—	210	μA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (MAX)$	30	—	—	μA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCIO}$	-30	—	—	μA
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \leq V_{IN} \leq V_{CCIO}$	—	—	210	μA
I_{BHHO}	Bus Hold High Overdrive Current	$0 \leq V_{IN} \leq V_{CCIO}$	—	—	-210	μA
V_{BHT}	Bus Hold Trip Points	$0 \leq V_{IN} \leq V_{IH} (MAX)$	$V_{IL} (MAX)$	—	$V_{IH} (MIN)$	V
$C1^4$	I/O Capacitance	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	5	8	pf
$C2^4$	Dedicated Input Capacitance	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	5	6	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. When used as V_{REF} maximum leakage = 25 μA
3. Applicable to general purpose I/Os in top and bottom banks.
4. T_A 25°C, $f = 1.0MHz$.

sysI/O Recommended Operating Conditions

Standard	V _{CCIO}			V _{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVC MOS 3.3 ²	3.135	3.3	3.465	—	—	—
LVC MOS 2.5 ²	2.375	2.5	2.625	—	—	—
LVC MOS 1.8	1.71	1.8	1.89	—	—	—
LVC MOS 1.5	1.425	1.5	1.575	—	—	—
LVC MOS 1.2 ²	1.14	1.2	1.26	—	—	—
LVTTL ²	3.135	3.3	3.465	—	—	—
PCI	3.135	3.3	3.465	—	—	—
SSTL18 ² Class I, II	1.71	1.8	1.89	0.833	0.9	0.969
SSTL2 ² Class I, II	2.375	2.5	2.625	1.15	1.25	1.35
SSTL3 ² Class I, II	3.135	3.3	3.465	1.3	1.5	1.7
HSTL ² 15 Class I	1.425	1.5	1.575	0.68	0.75	0.9
HSTL ² 18 Class I, II	1.71	1.8	1.89	0.816	0.9	1.08
LVDS ²	2.375	2.5	2.625	—	—	—
MLVDS25 ¹	2.375	2.5	2.625	—	—	—
LVPECL33 ^{1,2}	3.135	3.3	3.465	—	—	—
BLVDS25 ^{1,2}	2.375	2.5	2.625	—	—	—
RSDS ^{1,2}	2.375	2.5	2.625	—	—	—
SSTL18D_I ² , II ²	1.71	1.8	1.89	—	—	—
SSTL25D_I ² , II ²	2.375	2.5	2.625	—	—	—
SSTL33D_I ² , II ²	3.135	3.3	3.465	—	—	—
HSTL15D_I ²	1.425	1.5	1.575	—	—	—
HSTL18D_I ² , II ²	1.71	1.8	1.89	—	—	—

1. Inputs on chip. Outputs are implemented with the addition of external resistors.

2. Input on this standard does not depend on the value of V_{CCIO}.

LVPECL

The LatticeECP2/M devices support the differential LVPECL standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The LVPECL input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

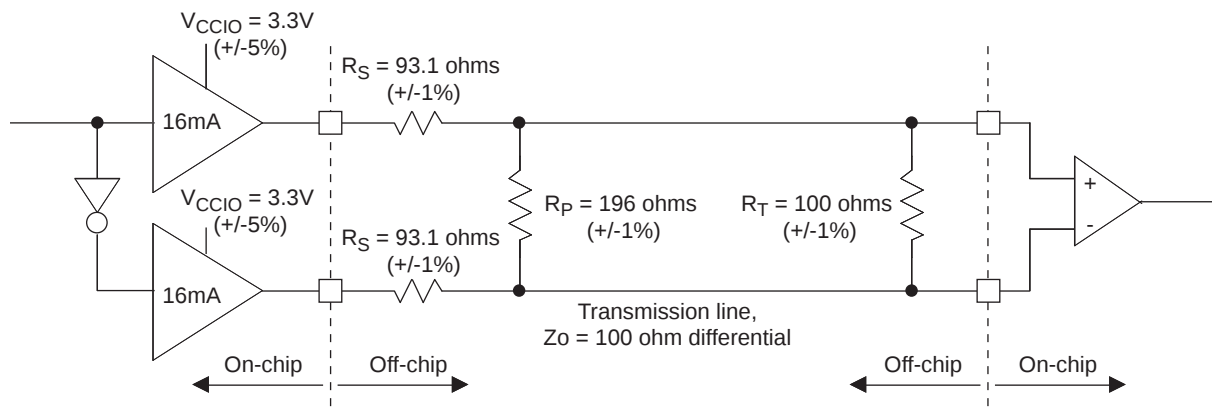


Table 3-4. LVPECL DC Conditions¹

Over Recommended Operating Conditions

Parameter	Description	Typical	Units
V_{CCIO}	Output Driver Supply (+/-5%)	3.30	V
Z_{OUT}	Driver Impedance	10	Ω
R_S	Driver Series Resistor (+/-1%)	93	Ω
R_P	Driver Parallel Resistor (+/-1%)	196	Ω
R_T	Receiver Termination (+/-1%)	100	Ω
V_{OH}	Output High Voltage	2.05	V
V_{OL}	Output Low Voltage	1.25	V
V_{OD}	Output Differential Voltage	0.80	V
V_{CM}	Output Common Mode Voltage	1.65	V
Z_{BACK}	Back Impedance	100.5	Ω
I_{DC}	DC Output Current	12.11	mA

1. For input buffer, see LVDS table.

LatticeECP2/M External Switching Characteristics⁹ (Continued)

Over Recommended Operating Conditions

Parameter	Description	Device	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t _{DIBSPI}	Data Invalid Before Clock (Transmit)	ECP2-20	—	280	—	280	—	280	ps
		ECP2-35	—	280	—	280	—	280	ps
		ECP2-50	—	280	—	280	—	280	ps
		ECP2-70	—	280	—	280	—	280	ps
		ECP2M20	—	230	—	230	—	230	ps
		ECP2M35	—	230	—	230	—	230	ps
		ECP2M50	—	230	—	230	—	230	ps
		ECP2M70	—	230	—	230	—	230	ps
		ECP2M100	—	230	—	230	—	230	ps
XGMII I/O Pin Parameters (312 Mbps) ⁵									
t _{SUXGMII}	Data Setup Before Read Clock	ECP2/M	480	—	480	—	480	—	ps
t _{HXGMII}	Data Hold After Read Clock	ECP2/M	480	—	480	—	480	—	ps
t _{DVBCKXGMII}	Data Valid Before Clock	ECP2/M	960	—	960	—	960	—	ps
t _{DVACKXGMII}	Data Valid After Clock	ECP2/M	960	—	960	—	960	—	ps
Primary									
f _{MAX_PRI} ⁷	Frequency for Primary Clock Tree	ECP2/M	—	420	—	357	—	311	MHz
t _{W_PRI}	Clock Pulse Width for Primary Clock	ECP2/M	0.95	—	1.19	—	2.00	—	ns
t _{SKEW_PRI}	Primary Clock Skew Within a Bank	ECP2/M	—	300	—	360	—	420	ps
Edge Clock									
f _{MAX_EDGE} ⁷	Frequency for Edge Clock	ECP2/M	—	420	—	357	—	311	MHz
t _{W_EDGE}	Clock Pulse Width for Edge Clock	ECP2/M	0.95	—	1.19	—	2.00	—	ns
t _{SKEW_EDGE}	Edge Clock Skew Within an Edge of the Device	ECP2/M	—	300	—	360	—	420	ps

- General timing numbers based on LVCMOS 2.5, 12mA, 0pf load.
- DDR timing numbers based on SSTL25 for BGA packages only.
- DDR2 timing numbers based on SSTL18 for BGA packages only.
- SPI4.2 and SFI4 timing numbers based on LVDS25 for BGA packages only.
- XGMII timing numbers based on HSTL class I. A corresponding left/right dedicated clock buffer is used when using the SPI4.2 interface to the left or right edge of the device. For SPI4.2 mode, the software tool will help in selecting the appropriate clock buffer.
- IP will be used to support DDR and DDR2 memory data rates down to 95MHz. This approach uses a free-running clock and PFU register to sample the data instead of the hardwired DDR memory interface.
- Using the LVDS I/O standard.
- ECP2-6 and ECP2-12 do not support SPI4.2
- The AC numbers do not apply to PCLK6 and PCLK7.
- Applies to CLKOP only.
- Please refer to TN1159, [LatticeECP2/M Pin Assignment Recommendations](#) for best performance.

LatticeECP2/M sysCONFIG Port Timing Specifications

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
sysCONFIG Byte Data Flow				
t_{SUCBDI}	Byte D[0:7] Setup Time to CCLK	7	—	ns
$t_{HCB DI}$	Byte D[0:7] Hold Time to CCLK	1	—	ns
t_{CODO}	CCLK to DOUT in Flowthrough Mode	—	12	ns
t_{SUCS}	CSN[0:1] Setup Time to CCLK	7	—	ns
t_{HCS}	CSN[0:1] Hold Time to CCLK	1	—	ns
t_{SUWD}	Write Signal Setup Time to CCLK	7	—	ns
t_{HWD}	Write Signal Hold Time to CCLK	1	—	ns
t_{DCB}	CCLK to BUSY Delay Time	—	12	ns
t_{CORD}	CCLK to Out for Read Data	—	12	ns
sysCONFIG Byte Slave Clocking				
t_{BSCH}	Byte Slave CCLK Minimum High Pulse	6	—	ns
t_{BSCL}	Byte Slave CCLK Minimum Low Pulse	9	—	ns
t_{BSCYC}	Byte Slave CCLK Cycle Time	15	—	ns
sysCONFIG Serial (Bit) Data Flow				
t_{SUSCDI}	DI Setup Time to CCLK Slave Mode	7	—	ns
t_{HSCDI}	DI Hold Time to CCLK Slave Mode	1	—	ns
t_{CODO}	CCLK to DOUT in Flowthrough Mode	—	12	ns
sysCONFIG Serial Slave Clocking				
t_{SSCH}	Serial Slave CCLK Minimum High Pulse	6	—	ns
t_{SSCL}	Serial Slave CCLK Minimum Low Pulse	6	—	ns
sysCONFIG POR, Initialization and Wake-up				
t_{ICFG}	Minimum Vcc to INITN High	—	28	ms
t_{VMC}	Time from t_{ICFG} to Valid Master CCLK	—	2	us
t_{PRGMRJ}	PROGRAMN Pin Pulse Rejection	—	8	ns
t_{PRGM}	PROGRAMN Low Time to Start Configuration	25	—	ns
t_{DINIT}	PROGRAMN High to INITN High Delay ¹	—	1.5	ms
$t_{DPPINIT}$	Delay Time from PROGRAMN Low to INITN Low	—	37	ns
$t_{DPPDONE}$	Delay Time from PROGRAMN Low to DONE Low	—	37	ns
t_{IODISS}	User I/O Disable from PROGRAMN Low	—	35	ns
t_{IOENSS}	User I/O Enabled Time from CCLK Edge During Wake-up Sequence	—	25	ns
t_{MWC}	Additional Wake Master Clock Signals after DONE Pin High	120	—	cycles
sysCONFIG SPI Port²				
t_{CFGX}	INITN High to CCLK Low	—	1	μs
t_{CSSPI}	INITN High to CSSPIN Low	—	2	us
t_{CSCCLK}	CCLK Low before CSSPIN Low	0	—	ns
t_{SOCDO}	CCLK Low to Output Valid	—	15	ns
t_{SOE}	CSSPIN[0:1] Active Setup Time	300	—	ns
t_{CSPID}	CSSPIN[0:1] Low to First CCLK Edge Setup Time	300+3cyc	600+6cyc	ns

LatticeECP2M Pin Information Summary, LFE2M20 and LFE2M35 (Cont.)

Pin Type		LFE2M20		LFE2M35		
		256 fpBGA	484 fpBGA	256 fpBGA	484 fpBGA	672 fpBGA
Available DDR-Interfaces per I/O Bank ¹	Bank0	0	0	0	0	0
	Bank1	0	0	0	0	0
	Bank2	0	1	0	1	3
	Bank3	0	1	0	1	2
	Bank4	2	4	2	4	3
	Bank5	1	2	1	2	3
	Bank6	0	3	0	1	2
	Bank7	1	2	1	2	3
	Bank8	0	0	0	0	0
PCI Capable I/Os per Bank	Bank0	0	0	0	0	0
	Bank1	0	0	0	0	0
	Bank2	0	0	0	0	0
	Bank3	0	0	0	0	0
	Bank4	32	62	32	62	50
	Bank5	20	28	20	28	60
	Bank6	16	40	16	39	52
	Bank7	28	40	28	40	60
	Bank8	0	0	0	0	0

1. Minimum requirement to implement a fully functional 8-bit wide DDR bus. Available DDR interface consists of at least 12 I/Os (1 DQS + 1 DQSB + 8 DQs + 1 DM + Bank VREF1).

LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-6E/SE					LFE2-12E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
M8	PB8B	5	PCLKC5_0/BDQ6	C	PB26B	5	PCLKC5_0/BDQ24	C
GND	GNDIO5	-			GNDIO5	-		
P7	PB13A	4	PCLKT4_0/BDQ15	T	PB31A	4	PCLKT4_0/BDQ33	T
R8	PB13B	4	PCLKC4_0/BDQ15	C	PB31B	4	PCLKC4_0/BDQ33	C
VCCIO	VCCIO4	4			VCCIO4	4		
T5	PB14A	4	BDQ15	T	PB32A	4	BDQ33	T
T6	PB14B	4	BDQ15	C	PB32B	4	BDQ33	C
T8	PB15A	4	BDQS15	T	PB33A	4	BDQS33	T
GND	GNDIO4	-			GNDIO4	-		
R7	PB16A	4	BDQ15	T	PB34A	4	BDQ33	T
T9	PB15B	4	BDQ15	C	PB33B	4	BDQ33	C
T7	PB16B	4	BDQ15	C	PB34B	4	BDQ33	C
L8	PB17A	4	BDQ15	T	PB35A	4	BDQ33	T
VCCIO	VCCIO4	4			VCCIO4	4		
P8	PB18A	4	BDQ15	T	PB36A	4	BDQ33	T
L9	PB17B	4	BDQ15	C	PB35B	4	BDQ33	C
N8	PB18B	4	BDQ15	C	PB36B	4	BDQ33	C
R9	PB19A	4	BDQ15	T	PB37A	4	BDQ33	T
GND	GNDIO4	-			GNDIO4	-		
R10	PB19B	4	BDQ15	C	PB37B	4	BDQ33	C
-	-	-			VCCIO	4		
-	-	-			GNDIO4	4		
N9	PB20A	4	BDQ24	T	PB47A	4	BDQ51	T
T10	PB21A	4	BDQ24	T	PB48A	4	BDQ51	T
M9	PB20B	4	BDQ24	C	PB47B	4	BDQ51	C
R11	PB21B	4	BDQ24	C	PB48B	4	BDQ51	C
P10	PB22A	4	BDQ24	T	PB49A	4	BDQ51	T
N11	PB23A	4	BDQ24	T	PB50A	4	BDQ51	T
VCCIO	VCCIO4	4			VCCIO4	4		
N10	PB22B	4	BDQ24	C	PB49B	4	BDQ51	C
P11	PB23B	4	BDQ24	C	PB50B	4	BDQ51	C
T11	PB24A	4	BDQS24	T	PB51A	4	BDQS51	T
GND	GNDIO4	-			GNDIO4	-		
M11	PB25A	4	BDQ24	T	PB52A	4	BDQ51	T
T12	PB24B	4	BDQ24	C	PB51B	4	BDQ51	C
L11	PB25B	4	BDQ24	C	PB52B	4	BDQ51	C
T13	PB26A	4	BDQ24	T	PB53A	4	BDQ51	T
R13	PB27A	4	BDQ24	T	PB54A	4	BDQ51	T
VCCIO	VCCIO4	4			VCCIO4	4		
T14	PB26B	4	BDQ24	C	PB53B	4	BDQ51	C
P13	PB27B	4	BDQ24	C	PB54B	4	BDQ51	C
GND	GNDIO4	-			GNDIO4	-		
N12	PB28A	4	VREF2_4/BDQ24	T	PB55A	4	VREF2_4/BDQ51	T
M12	PB28B	4	VREF1_4/BDQ24	C	PB55B	4	VREF1_4/BDQ51	C
R15	CFG2	8			CFG2	8		

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
AE17	PB51B	4	BDQ51	C	PB51B	4	BDQ51	C	
AB19	PB52A	4	BDQ51	T	PB52A	4	BDQ51	T	
AE19	PB52B	4	BDQ51	C	PB52B	4	BDQ51	C	
AF17	PB53A	4	BDQ51	T	PB53A	4	BDQ51	T	
AE18	PB53B	4	BDQ51	C	PB53B	4	BDQ51	C	
VCCIO	VCCIO4	4			VCCIO4	4			
W16	PB54A	4	BDQ51	T	PB54A	4	BDQ51	T	
AA17	PB54B	4	BDQ51	C	PB54B	4	BDQ51	C	
AF18	PB55A	4	BDQ51	T	PB55A	4	BDQ51	T	
AF19	PB55B	4	BDQ51	C	PB55B	4	BDQ51	C	
GND	GNDIO4	-			GNDIO4	-			
AA19	NC	-			PB56A	4	BDQ60	T	
W17	NC	-			PB56B	4	BDQ60	C	
Y19	NC	-			PB57A	4	BDQ60	T	
Y17	NC	-			PB57B	4	BDQ60	C	
AF20	NC	-			NC	-			
VCCIO	VCCIO4	4			VCCIO4	4			
AE20	NC	-			NC	-			
AA20	NC	-			NC	-			
W18	NC	-			NC	-			
AD20	NC	-			NC	-			
GND	GNDIO4	-			GNDIO4	-			
AE21	NC	-			NC	-			
AF21	NC	-			NC	-			
AF22	NC	-			NC	-			
VCCIO	VCCIO4	4			VCCIO4	4			
GND	GNDIO4	-			GNDIO4	-			
AE22	PB56A	4	BDQ60	T	PB65A	4	BDQ69	T	
AD22	PB56B	4	BDQ60	C	PB65B	4	BDQ69	C	
AF23	PB57A	4	BDQ60	T	PB66A	4	BDQ69	T	
AE23	PB57B	4	BDQ60	C	PB66B	4	BDQ69	C	
AD23	PB58A	4	BDQ60	T	PB67A	4	BDQ69	T	
AC23	PB58B	4	BDQ60	C	PB67B	4	BDQ69	C	
VCCIO	VCCIO4	4			VCCIO4	4			
AB20	PB59A	4	BDQ60	T	PB68A	4	BDQ69	T	
AC20	PB59B	4	BDQ60	C	PB68B	4	BDQ69	C	
GND	GNDIO4	-			GNDIO4	-			
AB21	PB60A	4	BDQS60	T	PB69A	4	BDQS69	T	
AC22	PB60B	4	BDQ60	C	PB69B	4	BDQ69	C	
W19	PB61A	4	BDQ60	T	PB70A	4	BDQ69	T	
AA21	PB61B	4	BDQ60	C	PB70B	4	BDQ69	C	
AF24	PB62A	4	BDQ60	T	PB71A	4	BDQ69	T	
AE24	PB62B	4	BDQ60	C	PB71B	4	BDQ69	C	
VCCIO	VCCIO4	4			VCCIO4	4			
Y20	PB63A	4	BDQ60	T	PB72A	4	BDQ69	T	
AB22	PB63B	4	BDQ60	C	PB72B	4	BDQ69	C	

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
AD18	PB66A	4	BDQ69	T
AF18	PB66B	4	BDQ69	C
AC18	PB67A	4	BDQ69	T
AE18	PB67B	4	BDQ69	C
VCCIO	VCCIO4	4		
AG19	PB68A	4	BDQ69	T
AH19	PB68B	4	BDQ69	C
GND	GNDIO4	-		
AE19	PB69A	4	BDQS69	T
AF19	PB69B	4	BDQ69	C
AC19	PB70A	4	BDQ69	T
AD19	PB70B	4	BDQ69	C
AJ19	PB71A	4	BDQ69	T
AK19	PB71B	4	BDQ69	C
VCCIO	VCCIO4	4		
AF20	PB72A	4	BDQ69	T
AH20	PB72B	4	BDQ69	C
AE20	PB73A	4	BDQ69	T
AG20	PB73B	4	BDQ69	C
GND	GNDIO4	-		
AD20	PB74A	4	BDQ78	T
AC20	PB74B	4	BDQ78	C
AH21	PB75A	4	BDQ78	T
AF21	PB75B	4	BDQ78	C
AJ20	PB76A	4	BDQ78	T
VCCIO	VCCIO4	4		
AK20	PB76B	4	BDQ78	C
AG21	PB77A	4	BDQ78	T
AE21	PB77B	4	BDQ78	C
AD21	PB78A	4	BDQS78	T
GND	GNDIO4	-		
AC21	PB78B	4	BDQ78	C
AD22	PB79A	4	BDQ78	T
AB21	PB79B	4	BDQ78	C
AJ21	PB80A	4	BDQ78	T
VCCIO	VCCIO4	4		
AK21	PB80B	4	BDQ78	C
GND	GNDIO4	-		
VCCIO	VCCIO4	4		
AJ25	PB87A	4	BDQS87***	T
AK24	PB87B	4	BDQ87	C
AJ24	PB88A	4	BDQ87	T
AK25	PB88B	4	BDQ87	C

LFE2M-20E/SE and LFE2M-35E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
T7	PB22A	4	PCLKT4_0/BDQ24	T	PB40A	4	PCLKT4_0/BDQ42	T
VCCIO	VCCIO4	4			VCCIO4	4		
T8	PB22B	4	PCLKC4_0/BDQ24	C	PB40B	4	PCLKC4_0/BDQ42	C
L7	PB23A	4	VREF2_4/BDQ24	T	PB41A	4	VREF2_4/BDQ42	T
L8	PB23B	4	VREF1_4/BDQ24	C	PB41B	4	VREF1_4/BDQ42	C
GNDIO	GNDIO4	-			GNDIO4	-		
VCCIO	VCCIO4	4			VCCIO4	4		
GNDIO	GNDIO4	-			GNDIO4	-		
P8	PB29A	4	BDQ33	T	PB47A	4	BDQ51	T
N8	PB29B	4	BDQ33	C	PB47B	4	BDQ51	C
R7	PB30A	4	BDQ33	T	PB48A	4	BDQ51	T
R8	PB30B	4	BDQ33	C	PB48B	4	BDQ51	C
N7	PB31A	4	BDQ33	T	PB49A	4	BDQ51	T
M8	PB31B	4	BDQ33	C	PB49B	4	BDQ51	C
VCCIO	VCCIO4	4			VCCIO4	4		
R9	PB32A	4	BDQ33	T	PB50A	4	BDQ51	T
T9	PB32B	4	BDQ33	C	PB50B	4	BDQ51	C
GNDIO	GNDIO4	-			GNDIO4	-		
T10	PB33A	4	BDQS33	T	PB51A	4	BDQS51	T
R10	PB33B	4	BDQ33	C	PB51B	4	BDQ51	C
N9	PB34A	4	BDQ33	T	PB52A	4	BDQ51	T
P10	PB34B	4	BDQ33	C	PB52B	4	BDQ51	C
VCCIO	VCCIO4	4			VCCIO4	4		
GNDIO	GNDIO4	-			GNDIO4	-		
L9	PB47A	4	BDQ51	T	PB65A	4	BDQ69	T
M9	PB47B	4	BDQ51	C	PB65B	4	BDQ69	C
T11	PB49A	4	BDQ51	T	PB67A	4	BDQ69	T
R11	PB49B	4	BDQ51	C	PB67B	4	BDQ69	C
VCCIO	VCCIO4	4			VCCIO4	4		
T12	PB50A	4	BDQ51	T	PB68A	4	BDQ69	T
T13	PB50B	4	BDQ51	C	PB68B	4	BDQ69	C
GNDIO	GNDIO4	-			GNDIO4	-		
P11	PB51A	4	BDQS51	T	PB69A	4	BDQS69	T
N10	PB51B	4	BDQ51	C	PB69B	4	BDQ69	C
T14	PB52A	4	BDQ51	T	PB70A	4	BDQ69	T
R13	PB52B	4	BDQ51	C	PB70B	4	BDQ69	C
R15	PB53A	4	BDQ51	T	PB71A	4	BDQ69	T
R16	PB53B	4	BDQ51	C	PB71B	4	BDQ69	C
VCCIO	VCCIO4	4			VCCIO4	4		
R14	PB54A	4	BDQ51	T	PB72A	4	BDQ69	T
P15	PB54B	4	BDQ51	C	PB72B	4	BDQ69	C
P16	PB55A	4	BDQ51	T	PB73A	4	BDQ69	T
P14	PB55B	4	BDQ51	C	PB73B	4	BDQ69	C
GNDIO	GNDIO4	-			GNDIO4	-		
L11	CFG2	8			CFG2	8		
L10	CFG1	8			CFG1	8		
P13	CFG0	8			CFG0	8		
N12	PROGRAMN	8			PROGRAMN	8		

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
Y22	PR60B	3		C	PR81B	3	RDQ82	C	
Y23	PR60A	3		T	PR81A	3	RDQ82	T	
AB26	NC	-			PR80B	3	RDQ82	C (LVDS)*	
AB27	NC	-			PR80A	3	RDQ82	T (LVDS)*	
-	-	-			VCCIO3	3			
Y24	NC	-			PR79B	3	RDQ82	C	
Y25	NC	-			PR79A	3	RDQ82	T	
AA29	NC	-			PR78B	3	RDQ82	C (LVDS)*	
Y28	NC	-			PR78A	3	RDQ82	T (LVDS)*	
Y30	NC	-			PR76B	3	RDQ73	C	
Y29	NC	-			PR76A	3	RDQ73	T	
-	-	-			GNDIO3	-			
-	-	-			-	-			
W22	NC	-			PR75B	3	RDQ73	C (LVDS)*	
V22	NC	-			PR75A	3	RDQ73	T (LVDS)*	
Y27	NC	-			PR74B	3	RDQ73	C	
-	-	-			VCCIO3	3			
Y26	NC	-			PR74A	3	RDQ73	T	
W30	NC	-			PR73B	3	RDQ73	C (LVDS)*	
W29	NC	-			PR73A	3	RDQS73	T (LVDS)*	
-	-	-			GNDIO3	-			
W25	NC	-			PR72B	3	RDQ73	C	
W26	NC	-			PR72A	3	RDQ73	T	
U29	PR59B	3		C (LVDS)*	PR71B	3	RDQ73	C (LVDS)*	
V29	PR59A	3		T (LVDS)*	PR71A	3	RDQ73	T (LVDS)*	
VCCIO	VCCIO3	3			VCCIO3	3			
V30	PR58B	3		C	PR70B	3	RDQ73	C	
U30	PR58A	3		T	PR70A	3	RDQ73	T	
W27	PR57B	3		C (LVDS)*	PR69B	3	RDQ73	C (LVDS)*	
W28	PR57A	3		T (LVDS)*	PR69A	3	RDQ73	T (LVDS)*	
V24	PR55B	3	RDQ52	C	PR67B	3	RDQ64	C	
V25	PR55A	3	RDQ52	T	PR67A	3	RDQ64	T	
GNDIO	GNDIO3	-			GNDIO3	-			
U28	PR54B	3	RDQ52	C (LVDS)*	PR66B	3	RDQ64	C (LVDS)*	
U27	PR54A	3	RDQ52	T (LVDS)*	PR66A	3	RDQ64	T (LVDS)*	
U23	PR53B	3	RDQ52	C	PR65B	3	RDQ64	C	
V23	PR53A	3	RDQ52	T	PR65A	3	RDQ64	T	
VCCIO	VCCIO3	3			VCCIO3	3			
V26	PR52B	3	RDQ52	C (LVDS)*	PR64B	3	RDQ64	C (LVDS)*	
U26	PR52A	3	RDQS52	T (LVDS)*	PR64A	3	RDQS64	T (LVDS)*	
U25	PR51B	3	RDQ52	C	PR63B	3	RDQ64	C	
GNDIO	GNDIO3	-			GNDIO3	-			
U24	PR51A	3	RDQ52	T	PR63A	3	RDQ64	T	
T30	PR50B	3	RDQ52	C (LVDS)*	PR62B	3	RDQ64	C (LVDS)*	
R30	PR50A	3	RDQ52	T (LVDS)*	PR62A	3	RDQ64	T (LVDS)*	
T23	PR49B	3	RDQ52	C	PR61B	3	RDQ64	C	
VCCIO	VCCIO3	3			VCCIO3	3			
T22	PR49A	3	RDQ52	T	PR61A	3	RDQ64	T	

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
AA1	PL81A	6	LDQS81	T (LVDS)*
GNDIO	GNDIO6	-		
AA2	PL81B	6	LDQ81	C (LVDS)*
Y3	PL82A	6	LDQ81	T
AB1	PL82B	6	LDQ81	C
VCCIO	VCCIO6	6		
Y9	PL83A	6	LDQ81	T (LVDS)*
Y8	PL83B	6	LDQ81	C (LVDS)*
Y7	PL84A	6	LDQ81	T
AA7	PL84B	6	LDQ81	C
GNDIO	GNDIO6	-		
VCCIO	VCCIO6	6		
AB2	PL95A	6	LDQ99	T (LVDS)*
AB3	PL95B	6	LDQ99	C (LVDS)*
AA5	PL96A	6	LDQ99	T
AA6	PL96B	6	LDQ99	C
AB4	PL97A	6	LDQ99	T (LVDS)*
VCCIO	VCCIO6	6		
AB5	PL97B	6	LDQ99	C (LVDS)*
AA8	PL98A	6	LDQ99	T
AA9	PL98B	6	LDQ99	C
AC1	PL99A	6	LLM0_GPLLT_IN_A**/LDQS99	T (LVDS)*
GNDIO	GNDIO6	-		
AC2	PL99B	6	LLM0_GPLLC_IN_A**/LDQ99	C (LVDS)*
AC4	PL100A	6	LLM0_GPLLT_FB_A/LDQ99	T
AC3	PL100B	6	LLM0_GPLLC_FB_A/LDQ99	C
VCCIO	VCCIO6	6		
AC7	PL101A	6	LLM0_GDLLT_IN_A**/LDQ99	T (LVDS)*
AC6	PL101B	6	LLM0_GDLLC_IN_A**/LDQ99	C (LVDS)*
AC5	PL102A	6	LLM0_GDLLT_FB_A/LDQ99	T
AD3	PL102B	6	LLM0_GDLLC_FB_A/LDQ99	C
GNDIO	GNDIO6	-		
AB8	LLM0_PLLCAP	6		
AD2	PL104A	6		T
AD1	PL104B	6		C
AE2	TCK	-		
AE1	TDI	-		
AF2	TMS	-		
AF1	TDO	-		
AG1	VCCJ	-		
AH1	LLC_SQ_VCCR3	14		
AK2	LLC_SQ_HDINP3	14		T
AJ1	LLC_SQ_VCCIB3	14		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
AJ30	LRC_SQ_VCCIB0	13		
AK29	LRC_SQ_HDINP0	13		T
AH30	LRC_SQ_VCCRX0	13		
AG27	CFG2	8		
AD25	CFG1	8		
AG28	CFG0	8		
AG30	PROGRAMN	8		
AG29	CCLK	8		
AC24	INITN	8		
AF27	DONE	8		
GNDIO	GNDIO8	-		
AF28	WRITEN***	8		
AE26	CS1N***	8		
AB23	CSN***	8		
AF29	D0/SPIFASTN***	8		
VCCIO	VCCIO8	8		
AF30	D1***	8		
AD26	D2***	8		
AE29	D3***	8		
GNDIO	GNDIO8	-		
AE30	D4***	8		
AD29	D5***	8		
AC25	D6***	8		
AD30	D7/SPID0***	8		
VCCIO	VCCIO8	8		
AA22	DI/CSSPI0N***	8		
AC26	DOUT/CSON/CSSPI1N***	8		
AA23	BUSY/SISPI***	8		
AB22	RLM0_PLLCAP	3		
AC27	PR102B	3	RLM0_GDLLC_FB_A/RDQ99	C
GNDIO	GNDIO3	-		
AC28	PR102A	3	RLM0_GDLLT_FB_A/RDQ99	T
AC29	PR101B	3	RLM0_GDLLC_IN_A**/RDQ99	C (LVDS)*
AC30	PR101A	3	RLM0_GDLLT_IN_A**/RDQ99	T (LVDS)*
AB30	PR100B	3	RLM0_GPLLC_IN_A**/RDQ99	C
VCCIO	VCCIO3	3		
AA30	PR100A	3	RLM0_GPLLT_IN_A**/RDQ99	T
AB29	PR99B	3	RLM0_GPLLC_FB_A/RDQ99	C (LVDS)*
AB28	PR99A	3	RLM0_GPLLT_FB_A/RDQS99	T (LVDS)*
GNDIO	GNDIO3	-		
Y22	PR98B	3	RDQ99	C
Y23	PR98A	3	RDQ99	T
AB26	PR97B	3	RDQ99	C (LVDS)*

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
A9	ULC_SQ_HDOUTP0	11		T
A10	ULC_SQ_VCCOB0	11		
B9	ULC_SQ_HDOUTN0	11		C
C9	ULC_SQ_VCCTX1	11		
B8	ULC_SQ_HDOUTN1	11		C
C8	ULC_SQ_VCCOB1	11		
A8	ULC_SQ_HDOUTP1	11		T
C12	ULC_SQ_VCCRX1	11		
B11	ULC_SQ_HDINN1	11		C
C11	ULC_SQ_VCCIB1	11		
A11	ULC_SQ_HDINP1	11		T
B7	ULC_SQ_VCCAUX33	11		
E7	ULC_SQ_REFCLKN	11		C
D7	ULC_SQ_REFCLKP	11		T
C7	ULC_SQ_VCCP	11		
A3	ULC_SQ_HDINP2	11		T
C3	ULC_SQ_VCCIB2	11		
B3	ULC_SQ_HDINN2	11		C
C2	ULC_SQ_VCCRX2	11		
A6	ULC_SQ_HDOUTP2	11		T
C6	ULC_SQ_VCCOB2	11		
B6	ULC_SQ_HDOUTN2	11		C
C5	ULC_SQ_VCCTX2	11		
B5	ULC_SQ_HDOUTN3	11		C
A4	ULC_SQ_VCCOB3	11		
A5	ULC_SQ_HDOUTP3	11		T
C4	ULC_SQ_VCCTX3	11		
B2	ULC_SQ_HDINN3	11		C
B1	ULC_SQ_VCCIB3	11		
A2	ULC_SQ_HDINP3	11		T
C1	ULC_SQ_VCCRX3	11		
L12	VCC	-		
L13	VCC	-		
L18	VCC	-		
L19	VCC	-		
M11	VCC	-		
M12	VCC	-		
M13	VCC	-		
M14	VCC	-		
M15	VCC	-		
M16	VCC	-		
M17	VCC	-		
M18	VCC	-		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
M2	PL26A	7	LDQ28	T (LVDS)*	PL30A	7	LDQ32	T (LVDS)*
M1	PL26B	7	LDQ28	C (LVDS)*	PL30B	7	LDQ32	C (LVDS)*
L6	PL27A	7	LDQ28	T	PL31A	7	LDQ32	T
L5	PL27B	7	LDQ28	C	PL31B	7	LDQ32	C
GNDIO	GNDIO7	-			GNDIO7	-		
L3	PL28A	7	LDQS28	T (LVDS)*	PL32A	7	LDQS32	T (LVDS)*
L4	PL28B	7	LDQ28	C (LVDS)*	PL32B	7	LDQ32	C (LVDS)*
M3	PL29A	7	LDQ28	T	PL33A	7	LDQ32	T
VCCIO	VCCIO7	7			VCCIO7	7		
M4	PL29B	7	LDQ28	C	PL33B	7	LDQ32	C
N1	PL30A	7	LDQ28	T (LVDS)*	PL34A	7	LDQ32	T (LVDS)*
N2	PL30B	7	LDQ28	C (LVDS)*	PL34B	7	LDQ32	C (LVDS)*
M5	PL31A	7	LDQ28	T	PL35A	7	LDQ32	T
GNDIO	GNDIO7	-			GNDIO7	-		
N6	PL31B	7	LDQ28	C	PL35B	7	LDQ32	C
P3	NC	-			PL37A	7		T (LVDS)*
-	-	-			GNDIO7	-		
P4	NC	-			PL37B	7		C (LVDS)*
P9	NC	-			PL38A	7		T
M7	NC	-			PL38B	7		C
-	-	-			VCCIO7	7		
P1	NC	-			PL39A	7		T (LVDS)*
P2	NC	-			PL39B	7		C (LVDS)*
N7	NC	-			PL40A	7		T
P7	NC	-			PL40B	7		C
-	-	-			GNDIO7	-		
P5	PL33A	7	LDQ37	T (LVDS)*	PL41A	7	LDQ45	T (LVDS)*
N5	PL33B	7	LDQ37	C (LVDS)*	PL41B	7	LDQ45	C (LVDS)*
P8	PL34A	7	LDQ37	T	PL42A	7	LDQ45	T
P6	PL34B	7	LDQ37	C	PL42B	7	LDQ45	C
VCCIO	VCCIO7	7			VCCIO7	7		
R3	PL35A	7	LDQ37	T (LVDS)*	PL43A	7	LDQ45	T (LVDS)*
R4	PL35B	7	LDQ37	C (LVDS)*	PL43B	7	LDQ45	C (LVDS)*
R10	PL36A	7	LDQ37	T	PL44A	7	LDQ45	T
P11	PL36B	7	LDQ37	C	PL44B	7	LDQ45	C
GNDIO	GNDIO7	-			GNDIO7	-		
R7	PL37A	7	LDQS37	T (LVDS)*	PL45A	7	LDQS45	T (LVDS)*
R8	PL37B	7	LDQ37	C (LVDS)*	PL45B	7	LDQ45	C (LVDS)*
R5	PL38A	7	LDQ37	T	PL46A	7	LDQ45	T
VCCIO	VCCIO7	7			VCCIO7	7		
T5	PL38B	7	LDQ37	C	PL46B	7	LDQ45	C
R1	PL39A	7	LDQ37	T (LVDS)*	PL47A	7	LDQ45	T (LVDS)*
R2	PL39B	7	LDQ37	C (LVDS)*	PL47B	7	LDQ45	C (LVDS)*
R11	PL40A	7	LDQ37	T	PL48A	7	LDQ45	T
GNDIO	GNDIO7	-			GNDIO7	-		
T10	PL40B	7	LDQ37	C	PL48B	7	LDQ45	C
T1	PL42A	7	LUM3_SPLLT_IN_A/LDQ46	T (LVDS)*	PL50A	7	LUM3_SPLLT_IN_A/LDQ54	T (LVDS)*
T2	PL42B	7	LUM3_SPLLC_IN_A/LDQ46	C (LVDS)*	PL50B	7	LUM3_SPLLC_IN_A/LDQ54	C (LVDS)*
U10	PL43A	7	LUM3_SPLLT_FB_A/LDQ46	T	PL51A	7	LUM3_SPLLT_FB_A/LDQ54	T

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GNDIO	GNDIO0	-			GNDIO0	-		
G15	PT41A	0		T	PT46A	0		T
J14	NC	-			PT45B	0		C
L15	NC	-			PT45A	0		T
H14	NC	-			PT44B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
K14	NC	-			PT44A	0		T
F15	PT38B	0		C	PT42B	0		C
G14	PT38A	0		T	PT42A	0		T
C15	PT37B	0		C	PT41B	0		C
GNDIO	GNDIO0	-			GNDIO0	-		
D14	PT37A	0		T	PT41A	0		T
G13	PT36B	0		C	PT40B	0		C
-	-	-			VCCIO0	0		
J13	PT36A	0		T	PT40A	0		T
B14	PT35B	0		C	PT39B	0		C
VCCIO	VCCIO0	0			-	-		
A14	PT35A	0		T	PT39A	0		T
F13	PT34B	0		C	PT38B	0		C
H13	PT34A	0		T	PT38A	0		T
D13	PT33B	0		C	PT37B	0		C
C14	PT33A	0		T	PT37A	0		T
GNDIO	GNDIO0	-			GNDIO0	-		
E13	PT32B	0		C	PT32B	0		C
D12	PT32A	0		T	PT32A	0		T
G12	PT31B	0		C	PT31B	0		C
E12	PT31A	0		T	PT31A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F12	NC	-			PT30B	0		C
D11	NC	-			PT30A	0		T
F11	NC	-			PT29B	0		C
E11	NC	-			PT29A	0		T
D7	ULC_SQ_VCCRX0	11			ULC_SQ_VCCRX0	11		
C9	ULC_SQ_HDINP0	11		T	ULC_SQ_HDINP0	11		T
B9	ULC_SQ_VCCIB0	11			ULC_SQ_VCCIB0	11		
C8	ULC_SQ_HDINN0	11		C	ULC_SQ_HDINN0	11		C
B8	ULC_SQ_VCCTX0	11			ULC_SQ_VCCTX0	11		
A9	ULC_SQ_HDOUTP0	11		T	ULC_SQ_HDOUTP0	11		T
D9	ULC_SQ_VCCOB0	11			ULC_SQ_VCCOB0	11		
A8	ULC_SQ_HDOUTN0	11		C	ULC_SQ_HDOUTN0	11		C
B7	ULC_SQ_VCCTX1	11			ULC_SQ_VCCTX1	11		
A7	ULC_SQ_HDOUTN1	11		C	ULC_SQ_HDOUTN1	11		C
E7	ULC_SQ_VCCOB1	11			ULC_SQ_VCCOB1	11		
A6	ULC_SQ_HDOUTP1	11		T	ULC_SQ_HDOUTP1	11		T
B6	ULC_SQ_VCCRX1	11			ULC_SQ_VCCRX1	11		
C7	ULC_SQ_HDINN1	11		C	ULC_SQ_HDINN1	11		C
D8	ULC_SQ_VCCIB1	11			ULC_SQ_VCCIB1	11		
C6	ULC_SQ_HDINP1	11		T	ULC_SQ_HDINP1	11		T
E6	ULC_SQ_VCCAUX33	11			ULC_SQ_VCCAUX33	11		

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M20E-5F484I	304	1.2V	-5	fpBGA	484	IND	20
LFE2M20E-6F484I	304	1.2V	-6	fpBGA	484	IND	20
LFE2M20E-5F256I	140	1.2V	-5	fpBGA	256	IND	20
LFE2M20E-6F256I	140	1.2V	-6	fpBGA	256	IND	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M35E-5F672I	410	1.2V	-5	fpBGA	672	IND	35
LFE2M35E-6F672I	410	1.2V	-6	fpBGA	672	IND	35
LFE2M35E-5F484I	303	1.2V	-5	fpBGA	484	IND	35
LFE2M35E-6F484I	303	1.2V	-6	fpBGA	484	IND	35
LFE2M35E-5F256I	140	1.2V	-5	fpBGA	256	IND	35
LFE2M35E-6F256I	140	1.2V	-6	fpBGA	256	IND	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M50E-5F900I	410	1.2V	-5	fpBGA	900	IND	50
LFE2M50E-6F900I	410	1.2V	-6	fpBGA	900	IND	50
LFE2M50E-5F672I	372	1.2V	-5	fpBGA	672	IND	50
LFE2M50E-6F672I	372	1.2V	-6	fpBGA	672	IND	50
LFE2M50E-5F484I	270	1.2V	-5	fpBGA	484	IND	50
LFE2M50E-6F484I	270	1.2V	-6	fpBGA	484	IND	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70E-5F1152I	436	1.2V	-5	fpBGA	1152	IND	70
LFE2M70E-6F1152I	436	1.2V	-6	fpBGA	1152	IND	70
LFE2M70E-5F900I	416	1.2V	-5	fpBGA	900	IND	70
LFE2M70E-6F900I	416	1.2V	-6	fpBGA	900	IND	70

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M100E-5F1152I	520	1.2V	-5	fpBGA	1152	IND	100
LFE2M100E-6F1152I	520	1.2V	-6	fpBGA	1152	IND	100
LFE2M100E-5F900I	416	1.2V	-5	fpBGA	900	IND	100
LFE2M100E-6F900I	416	1.2V	-6	fpBGA	900	IND	100

Date	Version	Section	Change Summary
August 2006 (cont.)	01.1 (cont.)	Pinout Information (cont.)	Added Information on: Available Device Resources per Packaged Device table.
		Ordering Information	Updated ordering part number table to include ECP2-12.
			Updated topside mark drawing.
September 2006	02.0	Multiple	Added information regarding LatticeECP2M support throughout.
September 2006	02.1	DC and Switching Characteristics	Added Receiver Total Jitter Tolerance Specification table.
			Removed power-up requirements for proper configuration footnote in Recommended Operating Conditions table.
December 2006	02.2	Introduction	LatticeECP2M Selection Guide table has been updated.
		Architecture	Figure 2-16. Per Region Secondary Clock Selection has been updated.
			Figure 2-39. Simplified Channel Block Diagram for SERDES and PCS has been updated.
		DC and Switching	Footnotes have been added to Recommended Operating Conditions.
			DC Electrical Characteristics table has been updated.
			Supply Current (Standby) tables have been updated.
			Initialization Supply Current table have been updated.
			Updated timing numbers to include LFE2-12E (rev A 0.08).
		Pinout Information	Updated to include the entire ECP2 device information as well as 256-fpBGA and 484-fpBGA pin information for the ECP2M35E.
		Ordering Information	Updated to include the entire ECP2 and ECP2M device ordering information.
February 2007	02.3	Architecture	Updated EBR Asynchronous Reset section.
March 2007	02.4	DC and Switching Characteristics	Power-sequencing footnotes have been added to the Recommended Operating Conditions. DDR2 performance has been updated to 266MHz.
March 2007	02.5	Introduction	Added "Security Series" to the LatticeECP2 and LatticeECP2M families.
		Architecture	Enhanced Configuration Option section updated.
		DC and Switching	Recommended Operating Conditions table - footnote 4 updated.
		Ordering Information	"Security Series" ordering part numbers added.
April 2007	02.6	Introduction	LatticeECP2M family table has been updated for user I/O counts.
		Ordering Information	LatticeECP2M family ordering part number section has been updated to add 1152-fpBGA package for the ECP2M70 and ECP2M100.
July 2007	02.7	Architecture	Updated text in Ripple Mode section.
		DC and Switching	ECP2/M Supply Current information has been updated. Typical Building Block Function Performance, External Switching Characteristics, Internal Switching Characteristics, Family Timing Adders, sysCLOCK GPLL Timing, sysCLOCK SPLL Timing, DLL Timing and sysCONFIG Port Timing Specifications have been updated (timing rev. A 0.10). SERDES timing information has been updated. PCI Express timing information has been updated.
		Pinout Information	Added LatticeECP2M20 pinout information.
August 2007	02.8	Introduction	1156-fpBGA package option has been removed from the LatticeECP2M family.
		Architecture	Table 2-16. Selectable Master Clock (CCLK) Frequencies During Configuration table has been updated.
		DC and Switching	Supply Current (Standby) table has been updated.
			DSP Function timing has been updated.